

SPECIFICATION

• Supplier : Samsung electro-mechanics • Samsung P/N : CL03B332KP3NNNC

• Product : Multi-layer Ceramic Capacitor • Description : CAP, 3.3nF, 10V, ±10%, X7R, 0201

A. Samsung Part Number

<u>CL</u> <u>03</u> <u>B</u> <u>332</u> <u>K</u> <u>P</u> <u>3</u> <u>N</u> <u>N</u> <u>N</u> <u>C</u> ① ② ③ ④ ⑤ ⑥ ⑦ ⑧ ⑨ ⑩ ⑪

1	Series	Samsung Multi-layer Ceramic Capacitor			
2	Size	0201 (inch code)	L: 0.6	± 0.03 mm	W: 0.3 ± 0.03 mm
3	Dielectric	X7R	8	Inner electrode	Ni
4	Capacitance	3.3 nF		Termination	Cu
⑤	Capacitance	±10 %		Plating	Sn 100% (Pb Free)
	tolerance		9	Product	Normal
6	Rated Voltage	10 V	10	Special	Reserved for future use
(7)	Thickness	0.3 ± 0.03 mm	(11)	Packaging	Cardboard Type, 7" reel

B. Samsung Reliablility Test and Judgement condition

	Performance	Test condition			
Capacitance	Within specified tolerance	1klb±10% 1.0±0.2Vrms			
Tan δ (DF)	0.05 max.				
Insulation	10,000Mohm or 100Mohm⋅ <i>μ</i> F	Rated Voltage 60~120 sec.			
Resistance	Whichever is Smaller				
Appearance	No abnormal exterior appearance	Microscope (×10)			
Withstanding	No dielectric breakdown or	250% of the rated voltage			
Voltage	mechanical breakdown				
Temperature	X7R				
Characterisitcs	(From -55 ℃ to 125 ℃, Capacitance change shoud be within ±15%)				
Adhesive Strength	No peeling shall be occur on the	200g·F, for 10±1 sec.			
of Termination	terminal electrode				
Bending Strength	Capacitance change: within ±12.5%	Bending to the limit (1mm)			
		with 1.0mm/sec.			
Solderability	More than 95% of terminal surface	1) Sn63Pb37 solder			
	is to be soldered newly	235±5°C, 5±0.5sec.			
		2) SnAg3.0Cu0.5 solder			
		245±5℃, 3±0.3sec.			
		(preheating : 80~120℃ for 10~30sec.)			
Resistance to	Capacitance change: within ±7.5%	Solder pot : 270±5℃, 10±1sec.			
Soldering heat	Tan δ, IR : initial spec.				

	Performance	Test condition	
Vibration Test	Capacitance change: within ±5%	Amplitude : 1.5mm	
	Tan δ, IR : initial spec.	From 10Hz to 55Hz (return : 1min.)	
		2hours × 3 direction (x, y, z)	
Humidity	Capacitance change: within ±12.5%	40±2℃, 90~95%RH, 500+12/-0hrs	
	Tan δ: 0.075 max		
	IR : 1000Mohm or 50Mohm $\cdot \mu$ F		
	Whichever is Smaller		
Moisture	Capacitance change: within ±12.5%	With rated voltage	
Resistance	Tan δ : 0.075 max	40±2℃, 90~95%RH, 500+12/-0hrs	
	IR: 500Mohm or 25Mohm · μF		
	Whichever is Smaller		
High Temperature	Capacitance change: within ±12.5%	With 200% of the rated voltage	
Resistance	Tan δ : 0.075 max	Max. operating temperature	
	IR: 1000Mohm or 50Mohm $\cdot \mu$ F		
	Whichever is Smaller	1000+48/-0hrs	
Temperature	Capacitance change: within ±7.5%	1 cycle condition	
Cycling	Tan δ, IR : initial spec.	Min. operating temperatur → 25 °C	
		→ Max. operating temperature → 25°C	
		5 cycle test	

C. Recommended Soldering method :

Reflow (Reflow Peak Temperature : 260±5 °C, 10sec. Max)

^{*} For the more detail Specification, Please refer to the Samsung MLCC catalogue.